

FQL40N50

500V N-Channel MOSFET

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, power factor correction, motor drive and welding machine.

Features

- 40A, 500V, $R_{DS(on)} = 0.11\Omega$ @ $V_{GS} = 10$ V
- Low gate charge (typical 155 nC)
- Low C_{RSS} (typical 95 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQL40N50	Units
V_{DSS}	Drain-Source Voltage	500	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	40	A
	- Continuous ($T_C = 100^\circ\text{C}$)	25	A
I_{DM}	Drain Current - Pulsed	(Note 1)	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	mJ
I_{AR}	Avalanche Current	(Note 1)	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	460	W
	- Derate above 25°C	3.7	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	0.27	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.1	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	30	$^\circ\text{C}/\text{W}$

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	500	--	--	V
$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	--	0.48	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 500 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$	--	--	1	μA
		$V_{\text{DS}} = 400 \text{ V}$, $T_C = 125^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{\text{GS}} = 30 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{\text{GS}} = -30 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$	--	--	-100	nA

On Characteristics

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250 \mu\text{A}$	3.0	--	5.0	V
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = 10 \text{ V}$, $I_D = 20 \text{ A}$	--	0.085	0.11	Ω
g_{FS}	Forward Transconductance	$V_{\text{DS}} = 50 \text{ V}$, $I_D = 20 \text{ A}$ (Note 4)	--	29	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{\text{DS}} = 25 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$, $f = 1.0 \text{ MHz}$	--	5800	7500	pF
C_{oss}	Output Capacitance		--	880	1150	pF
C_{rss}	Reverse Transfer Capacitance		--	95	120	pF

Switching Characteristics

$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}} = 250 \text{ V}$, $I_D = 40 \text{ A}$, $R_G = 25 \Omega$	--	140	290	ns
t_r	Turn-On Rise Time		--	440	890	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	350	700	ns
t_f	Turn-Off Fall Time		--	250	500	ns
Q_g	Total Gate Charge	$V_{\text{DS}} = 400 \text{ V}$, $I_D = 40 \text{ A}$, $V_{\text{GS}} = 10 \text{ V}$	--	155	200	nC
Q_{gs}	Gate-Source Charge		--	37	--	nC
Q_{gd}	Gate-Drain Charge		--	78	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	40	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	160	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_S = 40 \text{ A}$	--	--	1.4	V
t_{rr}	Reverse Recovery Time	$V_{\text{GS}} = 0 \text{ V}$, $I_S = 40 \text{ A}$, $dI_F / dt = 100 \text{ A}/\mu\text{s}$	--	520	--	ns
Q_{rr}	Reverse Recovery Charge		--	8.0	--	μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 2.0\text{mH}$, $I_{AS} = 40\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25 \Omega$. Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 40\text{A}$, $dI/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq \text{BV}_{\text{DSS}}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

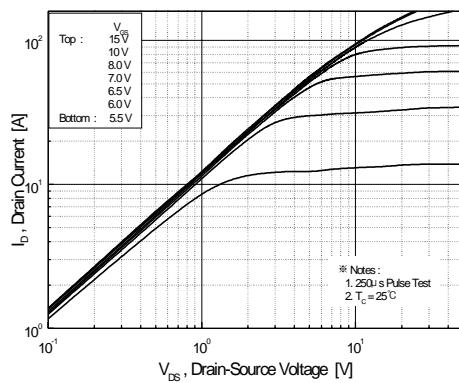


Figure 1. On-Region Characteristics

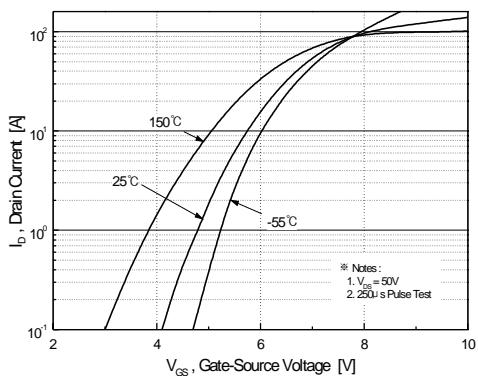


Figure 2. Transfer Characteristics

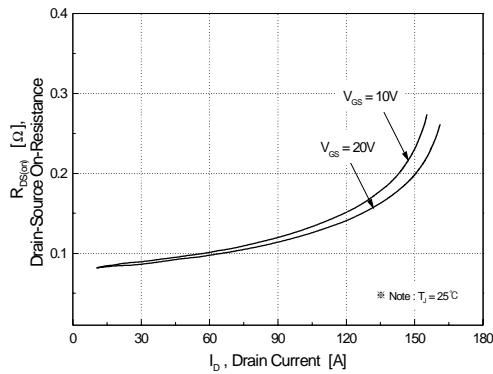


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

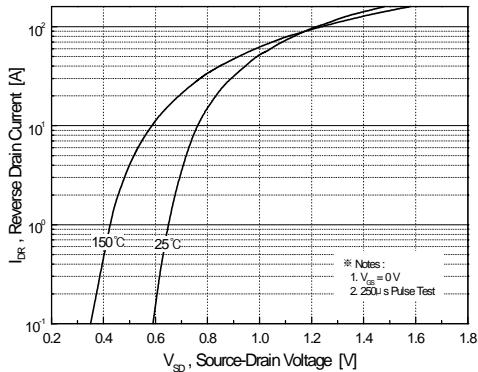


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

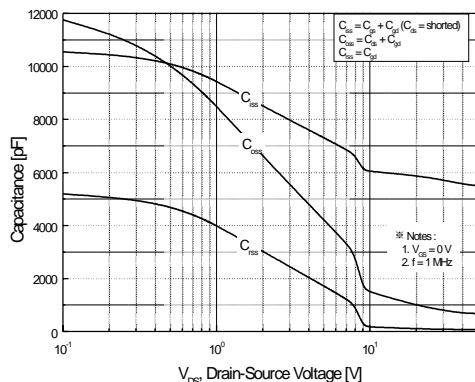


Figure 5. Capacitance Characteristics

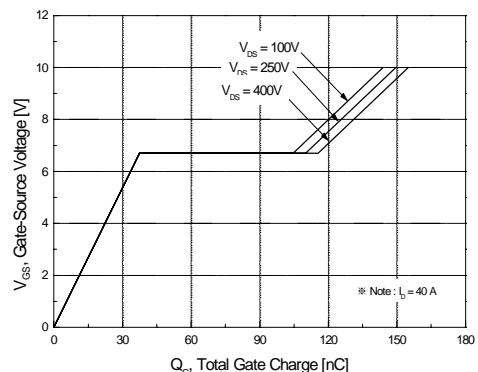


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

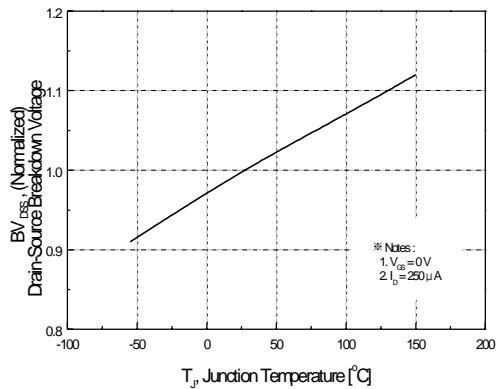


Figure 7. Breakdown Voltage Variation vs. Temperature

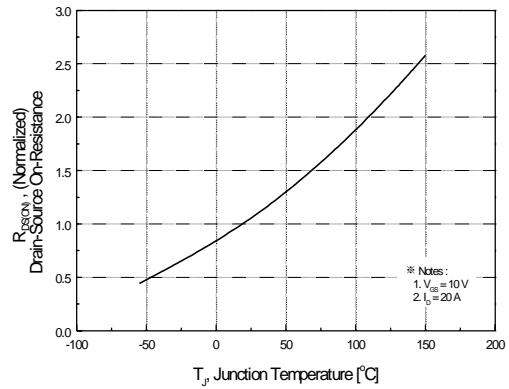


Figure 8. On-Resistance Variation vs. Temperature

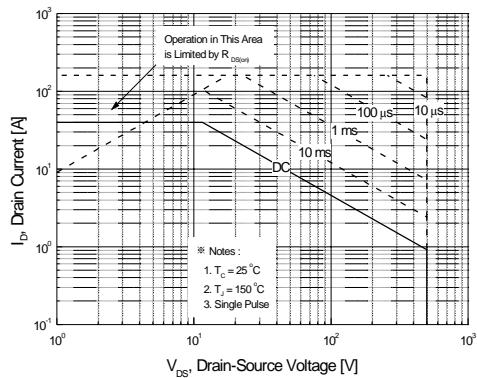


Figure 9. Maximum Safe Operating Area

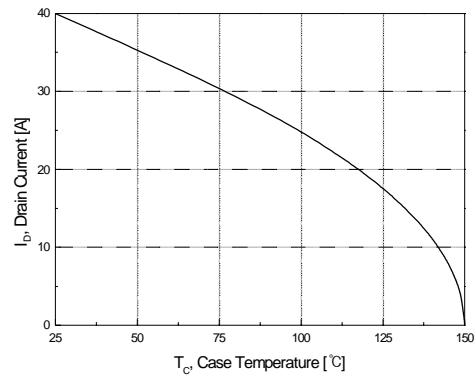


Figure 10. Maximum Drain Current vs. Case Temperature

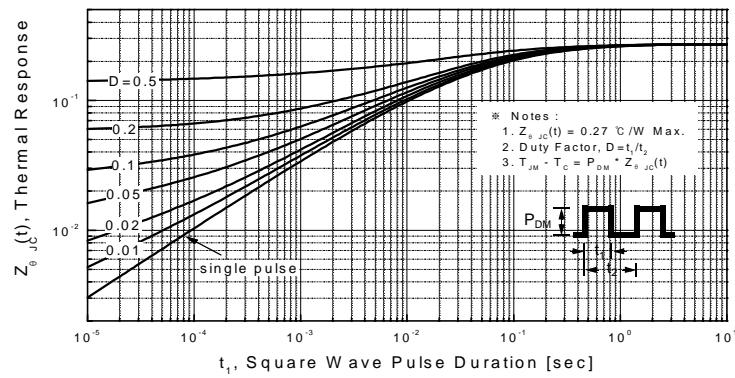
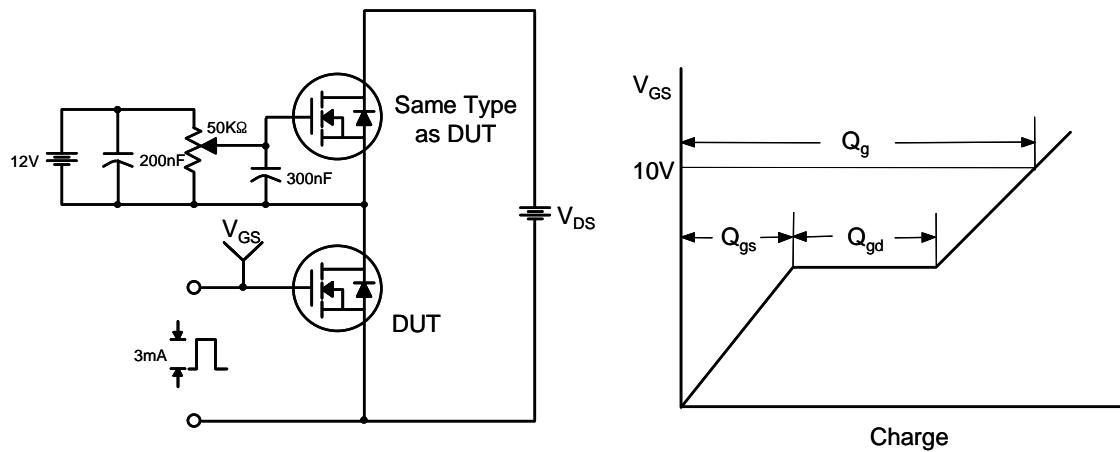
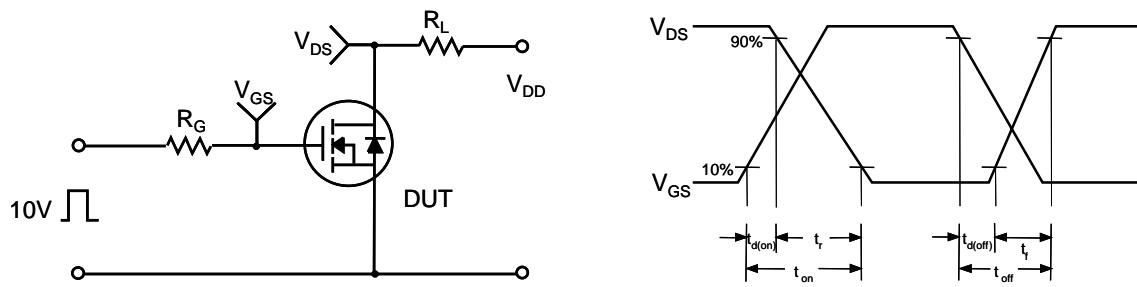
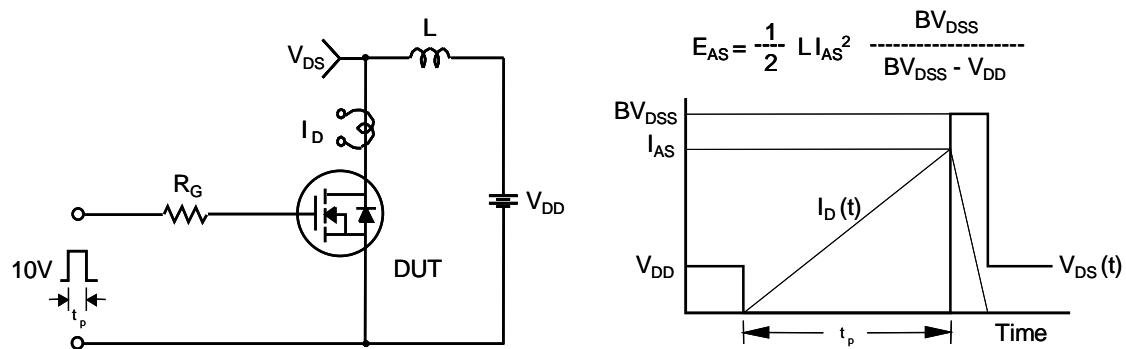
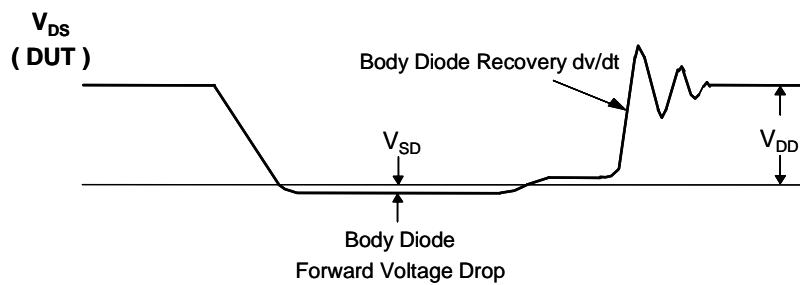
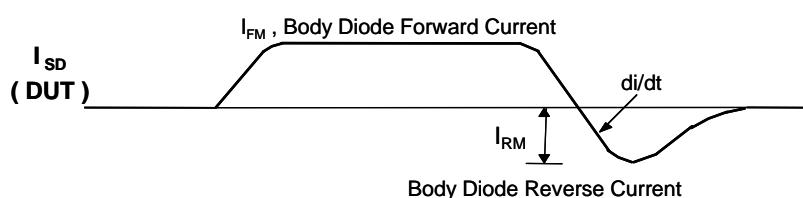
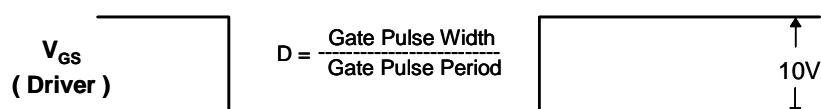
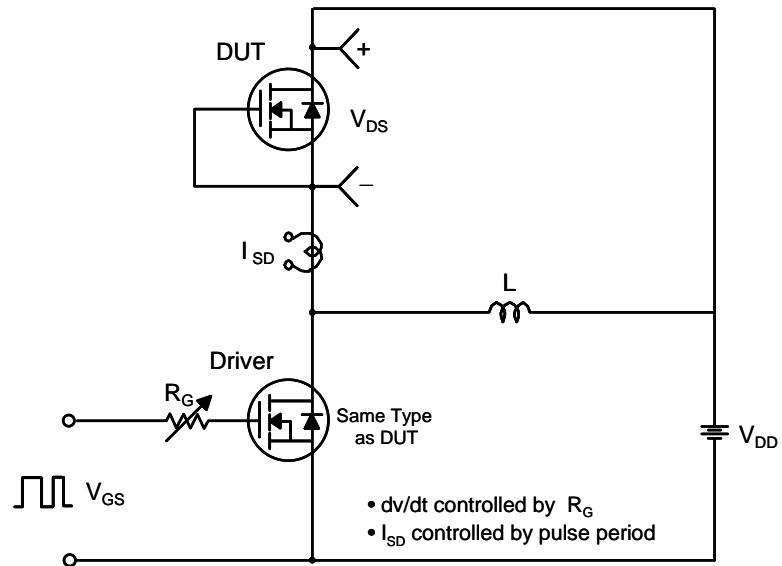


Figure 11. Transient Thermal Response Curve

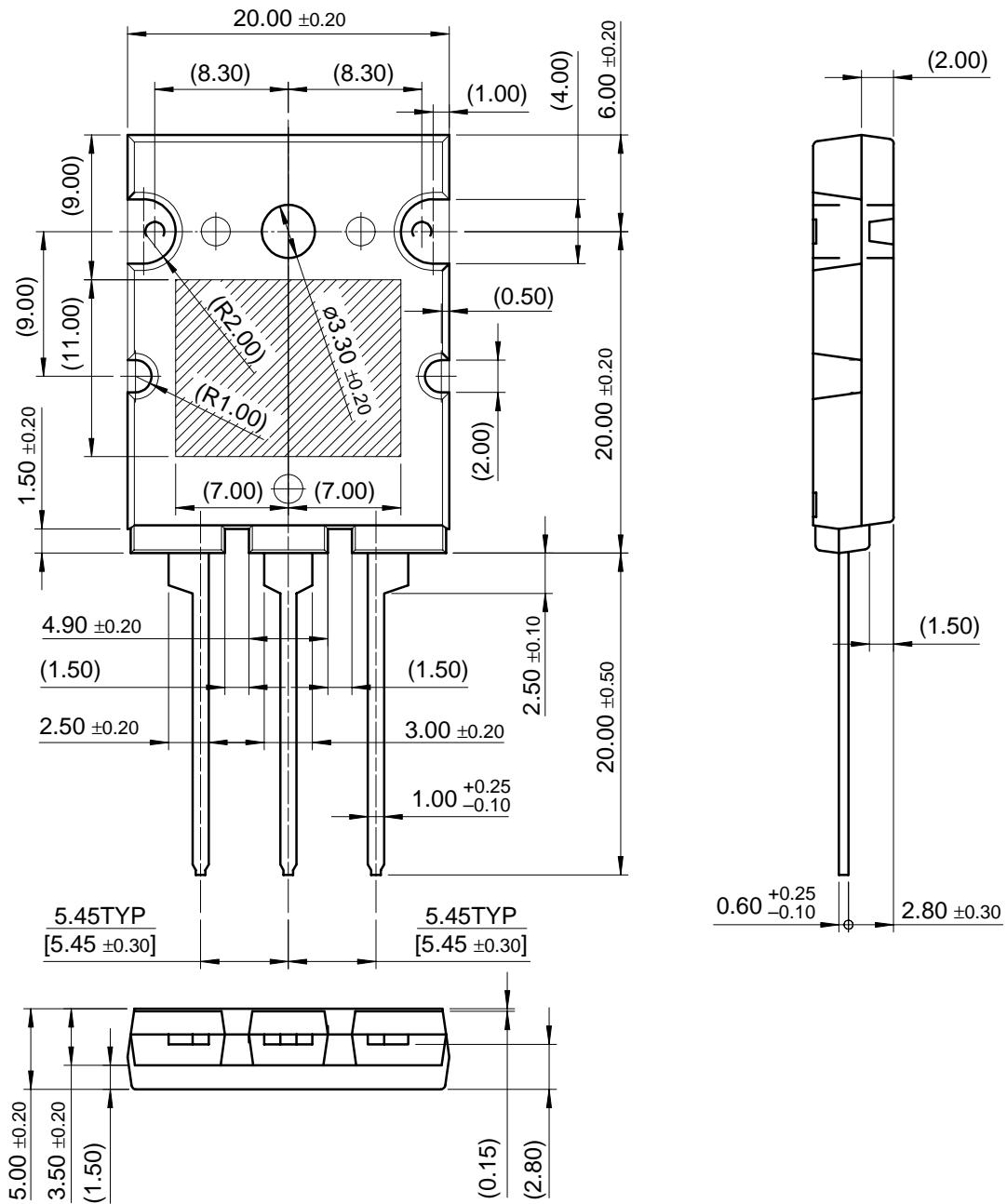
Gate Charge Test Circuit & Waveform**Resistive Switching Test Circuit & Waveforms****Unclamped Inductive Switching Test Circuit & Waveforms**

Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimensions

TO-264



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